

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-15 (canceled).

Claim 16 (new): An internal conductor connection structure comprising:
an insulator substrate;
line conductors disposed in the insulator substrate; and
at least two via conductors adjacent each other at a predetermined interval in the insulator substrate, at least one of the at least two via conductors including a continuous via conductor arranged to extend in a direction away from the other via conductor; wherein

the at least one of the at least two via conductors is connected to one of the line conductors through the continuous via conductor.

Claim 17 (new): The internal conductor connection structure according to Claim 16, wherein a connecting portion of the line conductor to the continuous via conductor or a connecting portion of the continuous via conductor that is connected to the line conductor is arranged to be a connecting land having an area larger than the connecting portion of the other conductor.

Claim 18 (new): A multilayer substrate comprising:
a laminate including a plurality of laminated insulator layers;
at least first and second via conductors extending inside the laminate from positions adjacent to each other at a predetermined interval from a first main surface of the laminate;

a first line conductor connected to the first via conductor, the first via conductor including a first continuous via conductor arranged to extend in a direction away from the second via conductor; wherein

the first via conductor is connected to the first line conductor through the first continuous via conductor.

Claim 19 (new): The multilayer substrate according to Claim 18, further comprising a third via conductor extending inside the laminate from the first main surface of the laminate, the second via conductor includes a second continuous via conductor arranged to extend in a direction away from both the first and third via conductors, wherein the second via conductor is connected to a second line conductor through the second continuous via conductor.

Claim 20 (new): The multilayer substrate according to Claim 19, wherein the first continuous via conductor and the second continuous via conductor are arranged in different insulator layers.

Claim 21 (new): The multilayer substrate according to Claim 19, wherein the first continuous via conductor and the second continuous via conductor are arranged in an insulator layer that is thinner than the other insulator layers.

Claim 22 (new): The multilayer substrate according to Claim 19, wherein the first continuous via conductor and the second continuous via conductor penetrate through their respective insulator layers.

Claim 23 (new): The multilayer substrate according to Claim 19, wherein the first continuous via conductor and the second continuous via conductor do not penetrate through their respective insulator layers.

Claim 24 (new): The multilayer substrate according to Claim 18, wherein a connecting portion of the first line conductor to the first continuous via conductor or a connecting portion of the first continuous via conductor to the first line conductor is arranged to be a connecting land larger than the connecting portion of the other conductor.

Claim 25 (new): The multilayer substrate according to Claim 19, wherein a connecting portion of the second continuous via conductor that is connected to the second line conductor or a connecting portion of the second line conductor that is connected to the second continuous via conductor is arranged to be a connecting land that is larger than the connecting portion of the other conductor.

Claim 26 (new): The multilayer substrate according to Claim 18, further comprising a surface electrode connected to each of the via conductors disposed on the first main surface.

Claim 27 (new): The multilayer substrate according to Claim 18, further comprising an electronic component mounted on the first main surface, and external terminal electrodes of the electronic component are connected to the first via conductor and the second via conductor exposed at the first main surface without any surface electrode.

Claim 28 (new): The multilayer substrate according to Claim 18, further comprising a mother board connected to the first main surface.

Claim 29 (new): The multilayer substrate according to Claim 18, wherein the insulator layer includes a low-temperature sinterable ceramic material.

Claim 30 (new): The multilayer substrate according to Claim 18, wherein each of the via conductors and the line conductors individually include an electrically conductive material containing silver or copper.

Claim 31 (new): The multilayer substrate according to Claim 18, wherein the first continuous via conductor only partially overlaps with the first via conductor.